

Remarks/Arguments

Applicant thanks Examiner Pham for his patient and careful examination of this application and the clear explanation of the claim rejections, and for the helpful advice in a phone interview on April 24, 2007. Applicant cancels claims 1-16 and 22-24 in this application. In response to the Final Office Action of January 19, 2007, applicant amends claim 18 following Examiner Pham's suggestion to make claim 18 more clear in describing the invention and overcome the 112 indefinite rejection.

The amendment also puts claim 18 in allowable form for the following reason:

Claim 18, as amended, requires the die attach material to cover the entire bottom surface of the semiconductor die, which is attached to the chip carrier with the die attach material. The Papathomas publication [U.S. 2002/015093], on the other hand, discloses an underfill material that fills the gap between a chip and a substrate after the die is attached to the substrate with C4 solder interconnections, and therefore the underfill material can not cover the portion of the chip surface that is occupied by the C4 solder interconnection.

Because the Papathomas publication does not disclose all the elements in claim 18, applicant respectfully submits that it does not anticipate claim 18 and claim 18 stands patentable over the Papathomas reference.

Claims 17, 19, 20, 21, and 25 properly depend from claim 18. Because claim 18 is not anticipated by the Papathomas reference, applicant respectfully submits that its dependent claims also must not be anticipated by the reference and stand patentable.

For the reason presented above, applicant respectfully submits that the application is in allowable form and respectfully requests that the amendments be entered and the pending claims 17 through 21, and claim 25 be allowed to issue.

Respectfully submitted,

/Yingsheng Tung/

Yingsheng Tung
Attorney for Applicant
Reg. No. 52,305

Texas Instruments Incorporated
P. O. Box 655474 MS 3999
Dallas, TX 75265
(972)917-5355